

Features

- BV_{CEO} > 60V
- Small Form Factor Thermally Efficient Package
 Enables Higher Density End Products
- I_C = 3A High Continuous Current
- I_{CM} = 6A Peak Pulse Current
- Low Saturation Voltage V_{CE(SAT)} < 250mV @ 1A
- Complementary PNP Type: DXTP07060BFG
- Rated to +175°C Ideal For High Temperature Environment
- Wettable Flank For Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)

PowerDI3333-8 (SWP) (Type UX)

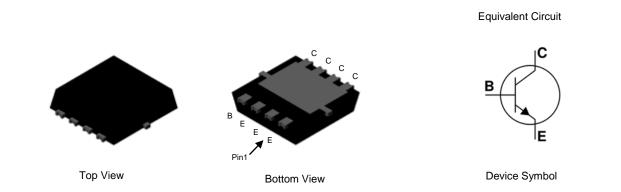
• Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic. "Green" Molding Compound UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Solderable per MIL-STD-202, Method 208 (63)
- Weight: 0.03 grams (Approximate)

Applications

- Load Switch
- Linear Regulator



Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
DXTN07060BFG-7	2H5	7	12	2,000
Notes: 1. No purposely add	led lead. Fully EU Directive 2002/9	5/EC (RoHS), 2011/65/EU (RoHS	2) & 2015/863/EU (RoHS 3) com	pliant.

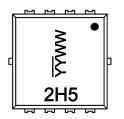
No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen - and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

<1000ppm antimony compounds. 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information

PowerDI3333-8 (SWP) (Type UX)



2H5= Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 18 = 2018) WW = Week Code (01 to 53)

PowerDI is a registered trademark of Diodes Incorporated.



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V _{CBO}	80	V
Collector-Emitter Voltage	V _{CEO}	60	V
Emitter-Base Voltage	V _{EBO}	7	V
Continuous Collector Current	Ι _C	3	А
Peak Pulse Current	I _{CM}	6	А

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
	(Note 5)		0.9	W
Power Dissipation	(Note 6)	PD	2.1	W
	(Note 7)		3.1	W
	(Note 5)		140	°C/W
Thermal Resistance, Junction to Ambient	(Note 6)	R _{θJA}	65	°C/W
	(Note 7)		44	°C/W
Thermal Resistance, Junction to Leads (Note 8)		R _{θJL}	8.5	°C/W
Operating and Storage Temperature Range		T _J , T _{STG}	-55 to +175	°C

ESD Ratings (Note 9)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	ЗA
Electrostatic Discharge - Machine Model	ESD MM	400	V	С
Notes: 5. For a device mounted with the collector tab on MRP FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.				

For a device mounted with the collector tab on MRP FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state. 5.

Same as Note 5, except the device is mounted on 25mm x 25mm 2oz copper. Same as Note 5, except the device is mounted on 50mm x 50mm 2oz copper. 6. 7.

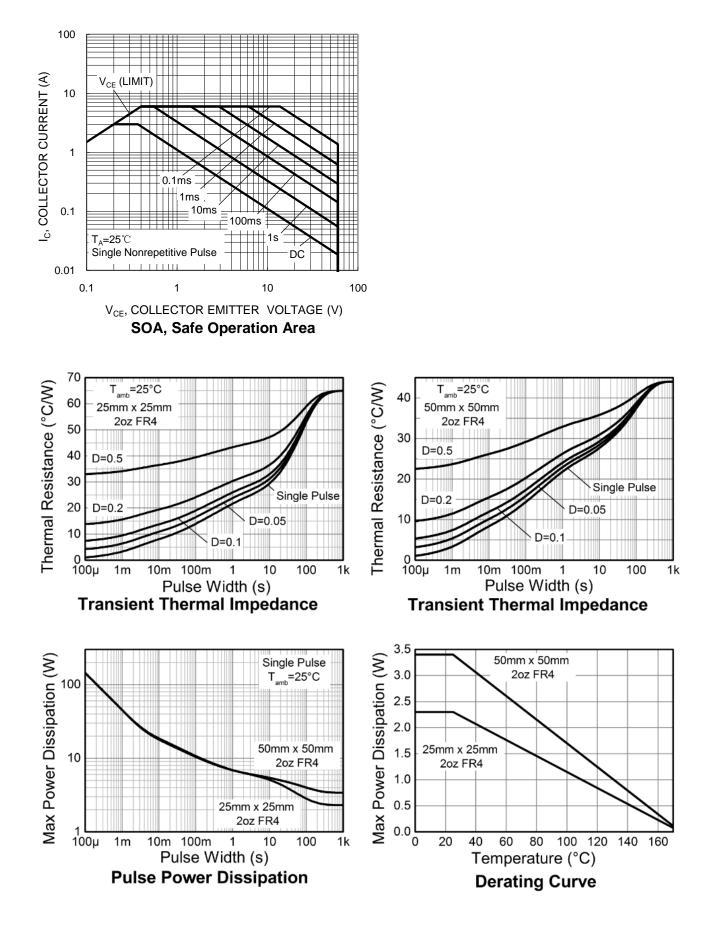
Thermal resistance from junction to solder-point (at the collector tab).

8. 9.

Refer to JEDEC specification JESD22-A114 and JESD22-A115.



Thermal Characteristics and Derating Information





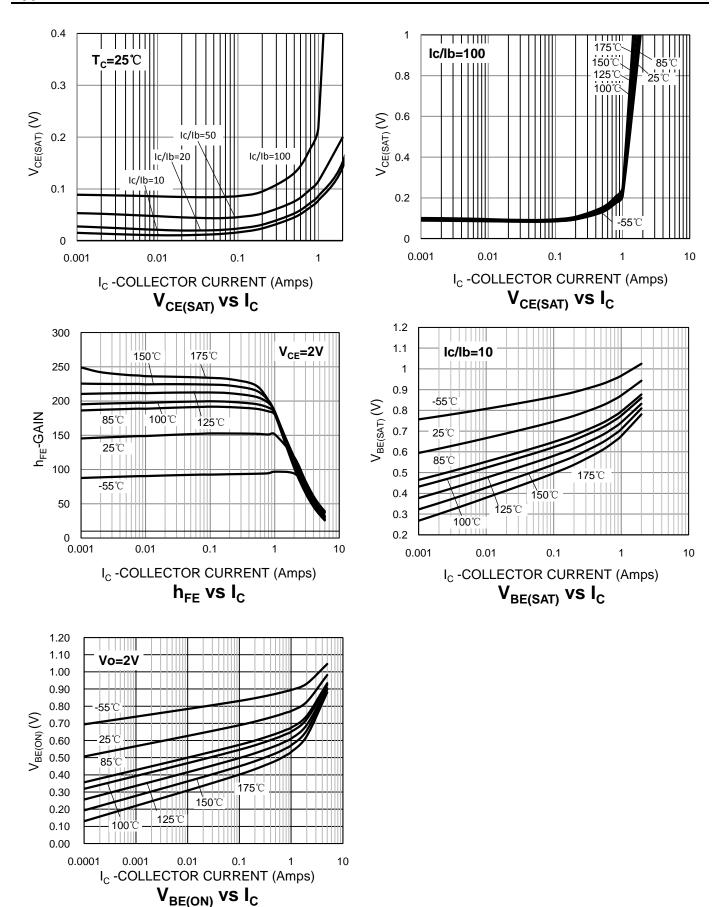
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CBO}	80	195		V	I _C = 100μA
Collector-Emitter Breakdown Voltage (Note 10)	BV _{CEO}	60	80		V	$I_{\rm C} = 10 {\rm mA}$
Emitter-Base Breakdown Voltage	BV _{EBO}	7	8.3	_	V	I _E = 100μA
	Ісво	_	_	20	nA	$V_{CB} = 60V$
Collector Cut-Off Current		_	—	10	μA	V _{CB} = 60V, T _A = +125°C
Emitter Cut-Off Current	I _{EBO}	_	—	20	nA	V _{EB} = 6V
Collector Emitter Seturation Voltage (Note 10)		_	78	250		$I_{\rm C} = 1$ A, $I_{\rm B} = 100$ mA
Collector-Emitter Saturation Voltage (Note 10)	VCE(SAT)	_	200	500	mV	I _C = 3A, I _B = 300mA
Base-Emitter Saturation Voltage (Note 10)	V _{BE(SAT)}	_	0.86	1.1	V	$I_{\rm C} = 1$ A, $I_{\rm B} = 100$ mA
Base-Emitter Turn-On Voltage (Note 10)	V _{BE(ON)}	_	0.79	0.95	V	$I_C = 1A, V_{CE} = 2V$
	h _{FE}	70	152	—		$I_{C} = 50 \text{mA}, V_{CE} = 2 \text{V}$
DC Current Coin (Note 10)		100	150	300		$I_{C} = 500 \text{mA}, V_{CE} = 2 \text{V}$
DC Current Gain (Note 10)		80	147			$I_C = 1A, V_{CE} = 2V$
		40	117			$I_C = 2A, V_{CE} = 2V$
Current Gain-Bandwidth Product	f _T	140	175	_	MHz	$V_{CE} = 5V, I_C = 100mA,$ f = 100MHz
Switching Times	t _{ON}	_	45	—		I _C = 500mA, V _{CC} = 10V,
Switching Times	toff	—	800		ns	$I_{B1} = -I_{B2} = 50 \text{mA}$
Output Capacitance	COBO	_	_	30	pF	$V_{CB} = 10V$, f = 1MHz

Note: 10. Measured under pulsed conditions. Pulse width \leq 300µs. Duty cycle \leq 2%.



Typical Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

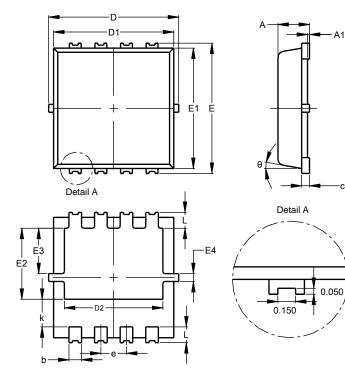




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)

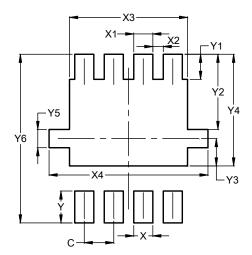


PowerDI3333-8 (SWP)						
	(Type UX)					
Dim	Min	Max	Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05				
b	0.25	0.40	0.32			
C	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
Е	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	-	0.65			
k	0.50	0.90	0.70			
L	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)		
С	0.650		
Х	0.420		
X1	0.420		
X2	0.230		
X3	2.600		
X4	3.500		
Y	0.700		
Y1	0.550		
Y2	1.650		
Y3	0.600		
Y4	2.450		
Y5	0.400		
Y6	3.700		

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device terminals and PCB tracking.



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